

# Power Rectifier

## MURHD560T4G, MURHD560W1T4G,

### Features and Benefits

- Ultrafast 30 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 Volts
- SURHD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Applications

- Power Supplies
- Inverters
- Free Wheeling Diodes

### Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 0.4 g (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
  - ◆ Machine Model = C (> 400 V)
  - ◆ Human Body Model = 3B (> 8000 V)

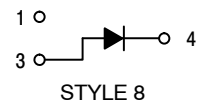
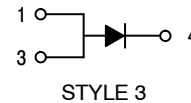
## ULTRAFAST RECTIFIER

### 5.0 AMPERES

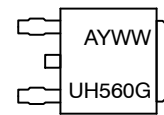
### 600 VOLTS



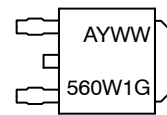
DPAK  
CASE 369C  
STYLES 3, 8



### MARKING DIAGRAM



STYLE 3



STYLE 8

UH560 = MURHD560T4  
 560W1 = MURHD560W1T4  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 G = Pb-Free Package

\* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejector pin), the front side assembly code may be blank.

### ORDERING INFORMATION

| Device          | Package        | Shipping†          |
|-----------------|----------------|--------------------|
| MURHD560T4G     | DPAK (Pb-Free) | 2500 / Tape & Reel |
| MURHD560W1T4G   | DPAK (Pb-Free) | 2500 / Tape & Reel |
| SSURHD8560W1T4G | DPAK (Pb-Free) | 2500 / Tape & Reel |

### DISCONTINUED (Note 1)

|                    |                |                    |
|--------------------|----------------|--------------------|
| SURHD8560T4G       | DPAK (Pb-Free) | 2500 / Tape & Reel |
| SURHD8560W1T4G     | DPAK (Pb-Free) | 2500 / Tape & Reel |
| SSURHD8560T4G-VF01 | DPAK (Pb-Free) | 2500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

1. **DISCONTINUED:** This device is not recommended for new design. Please contact your onsemi representative for information. The most current information on this device may be available on [www.onsemi.com](http://www.onsemi.com).

# MURHD560T4G, MURHD560W1T4G,

## MAXIMUM RATINGS

| Rating                                                                                                      | Symbol                          | Value       | Unit             |
|-------------------------------------------------------------------------------------------------------------|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                      | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 600         | V                |
| Average Rectified Forward Current<br>(Rated $V_R$ , $T_C = 159^\circ\text{C}$ )                             | $I_{F(AV)}$                     | 5.0         | A                |
| Non-Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | $I_{FSM}$                       | 50          | A                |
| Operating Junction and Storage Temperature Range                                                            | $T_J$ , $T_{stg}$               | -65 to +175 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

| Rating                                                   | Symbol          | Value | Unit               |
|----------------------------------------------------------|-----------------|-------|--------------------|
| Maximum Thermal Resistance, Junction to Case             | $R_{\theta JC}$ | 2.5   | $^\circ\text{C/W}$ |
| Maximum Thermal Resistance, Junction to Ambient (Note 1) | $R_{\theta JA}$ | 49.5  | $^\circ\text{C/W}$ |

1. Rating applies when surface mounted on a 1.5 mm FR4 PC board with a 1 oz. thick, 700 mm<sup>2</sup> Cu area.

## ELECTRICAL CHARACTERISTICS

| Rating                                                                                                                                              | Symbol   | Value       | Unit          |
|-----------------------------------------------------------------------------------------------------------------------------------------------------|----------|-------------|---------------|
| Maximum Instantaneous Forward Voltage (Note 2)<br>( $I_F = 5.0$ Amps, $T_C = 25^\circ\text{C}$ )<br>( $I_F = 5.0$ Amps, $T_C = 125^\circ\text{C}$ ) | $V_F$    | 2.7<br>1.65 | V             |
| Maximum Instantaneous Reverse Current (Note 2)<br>(Rated dc Voltage, $T_C = 25^\circ\text{C}$ )<br>(Rated dc Voltage, $T_C = 125^\circ\text{C}$ )   | $I_R$    | 10<br>70    | $\mu\text{A}$ |
| Maximum Reverse Recovery Time<br>( $I_F = 1.0$ Amp, $di/dt = 50$ Amps/ $\mu\text{s}$ , $V_R = 30$ V, $T_J = 25^\circ\text{C}$ )                     | $t_{rr}$ | 30          | ns            |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

# MURHD560T4G, MURHD560W1T4G,

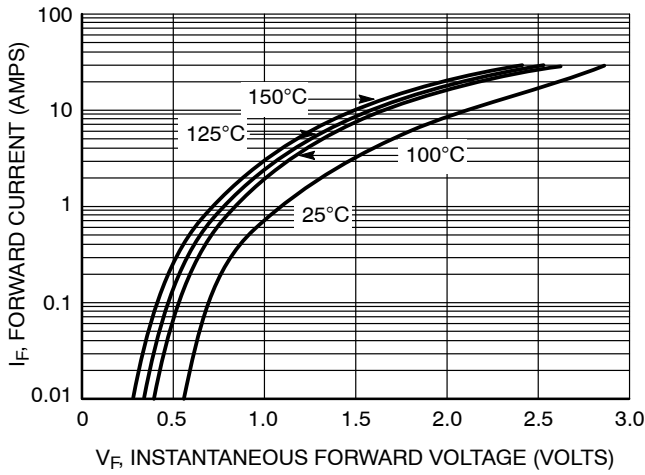


Figure 1. Typical Forward Voltage

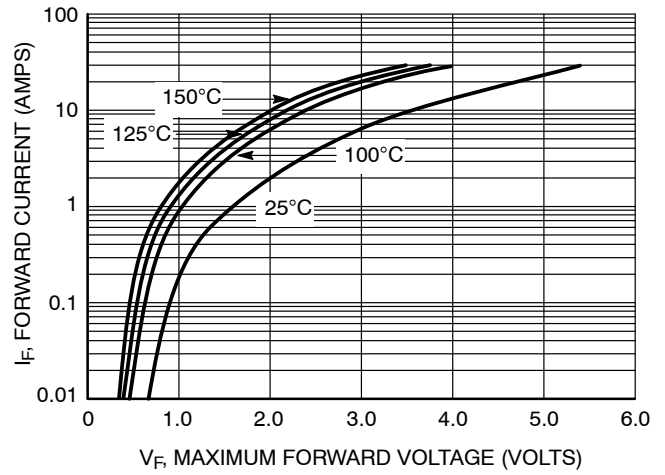


Figure 2. Maximum Forward Voltage

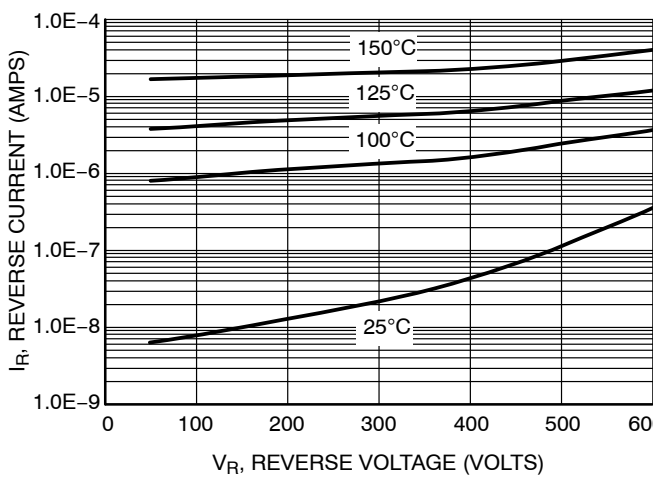


Figure 3. Typical Reverse Current

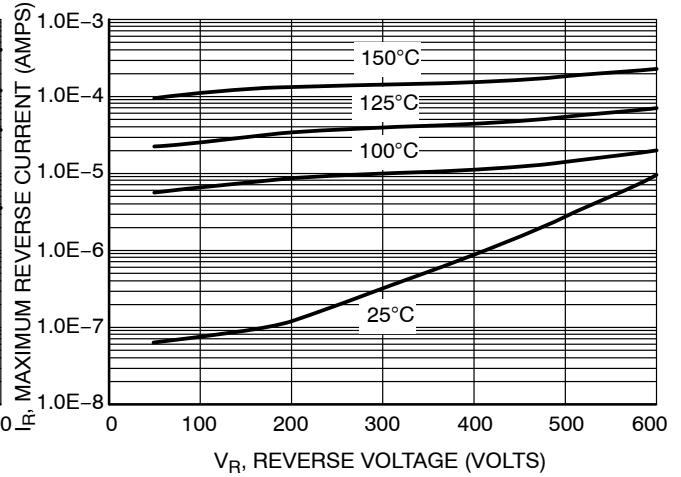


Figure 4. Maximum Reverse Current

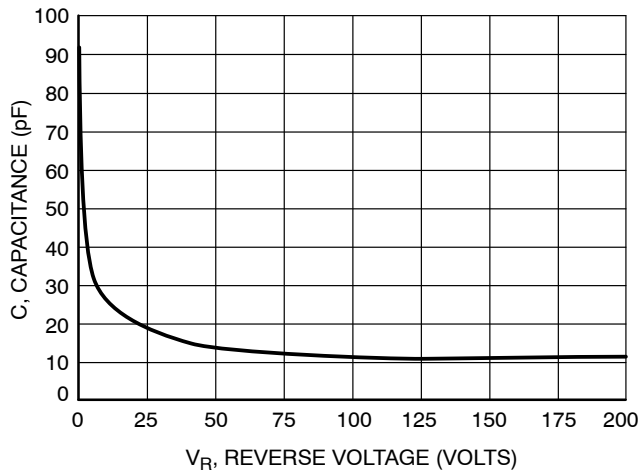


Figure 5. Typical Capacitance

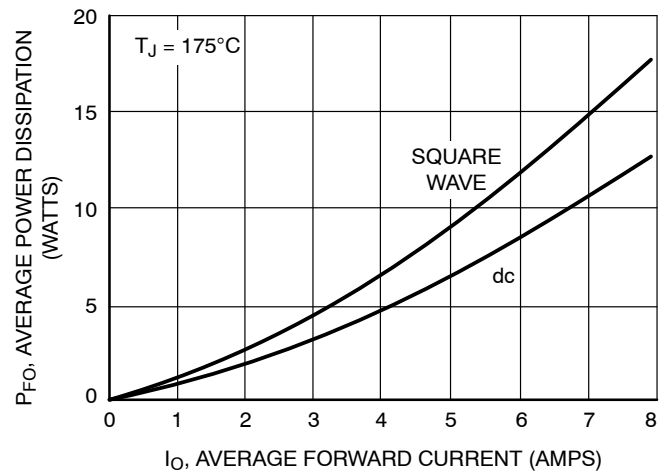


Figure 6. Forward Power Dissipation

# MURHD560T4G, MURHD560W1T4G,

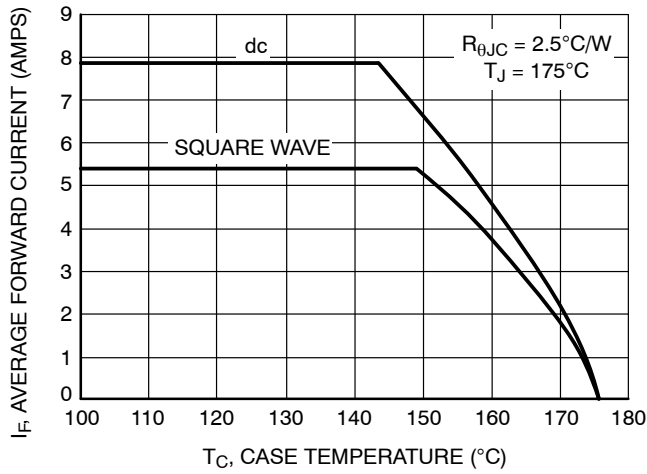


Figure 7. Current Derating

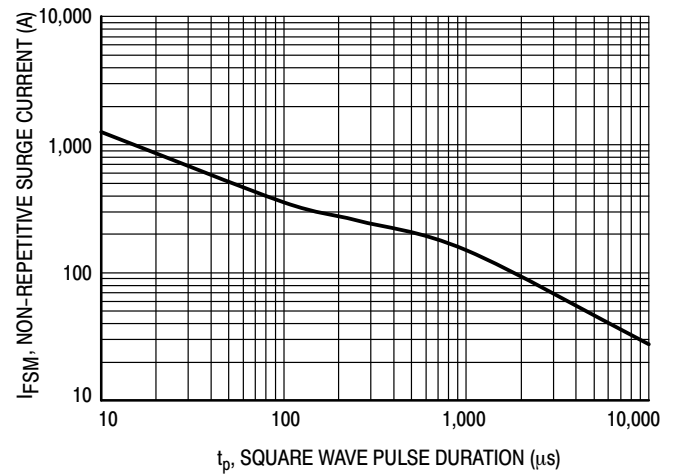


Figure 8. Typical Non-Repetitive Surge Current

\* Typical performance based on a limited sample size. ON Semiconductor does not guarantee ratings not listed in the Maximum Ratings table.

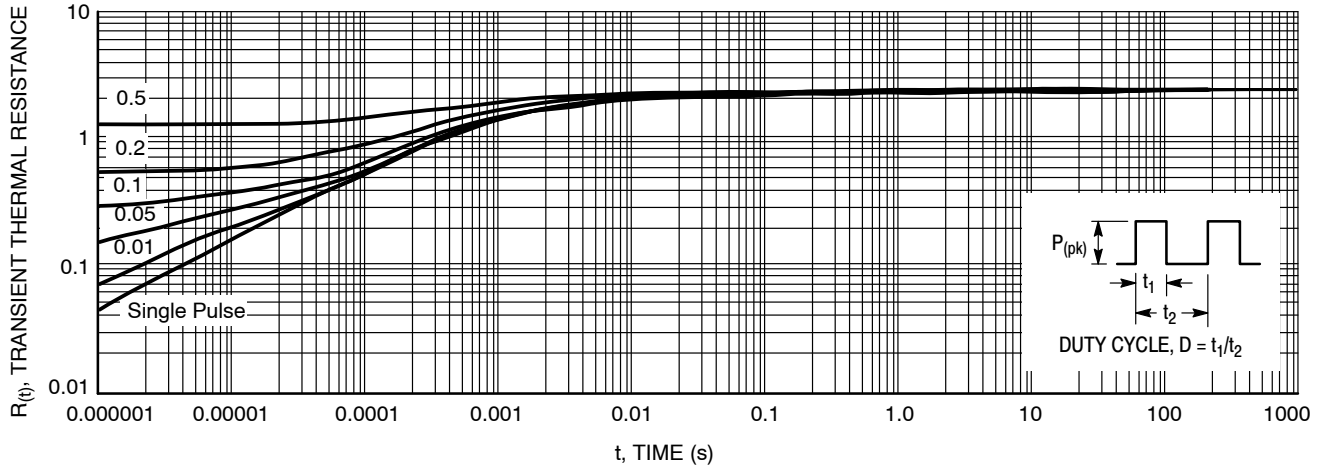


Figure 9. Thermal Response, Junction to Case

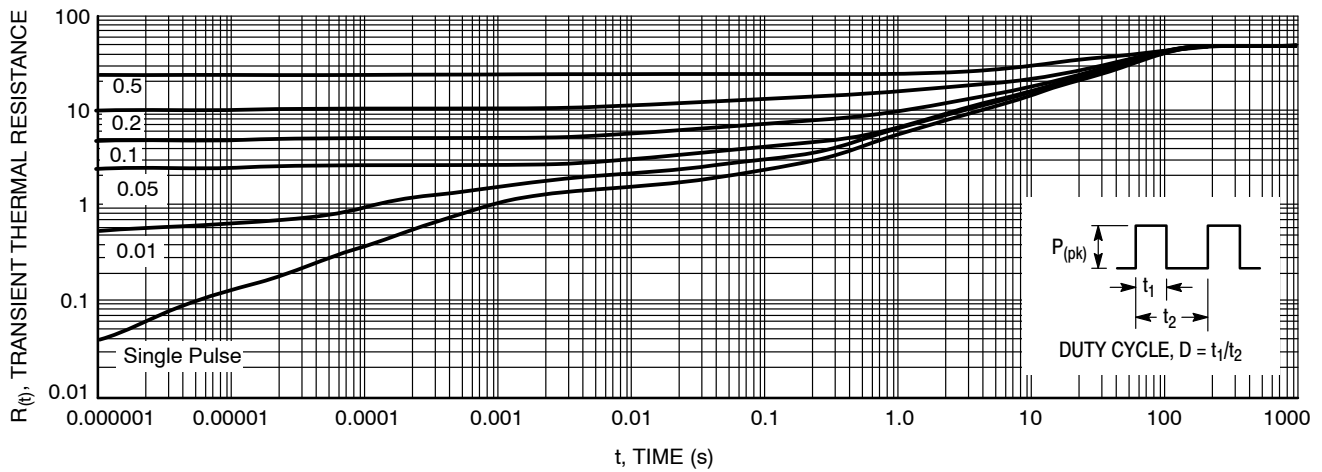
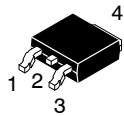
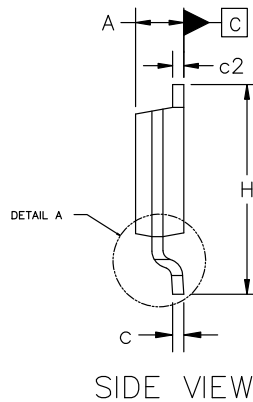
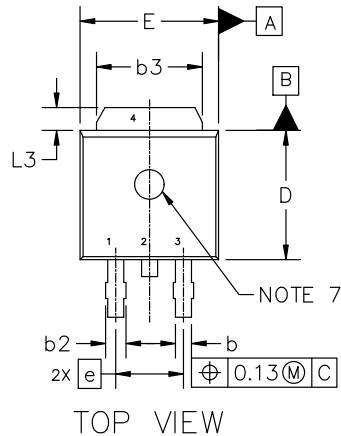


Figure 10. Thermal Response, Junction to Ambient

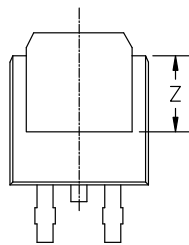

**DPAK-3 6.10x6.54x2.28, 2.29P**  
**CASE 369C**  
**ISSUE K**

DATE 14 MAY 2026

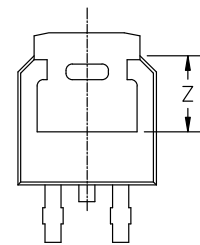
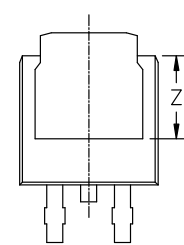
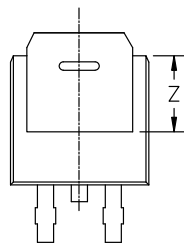
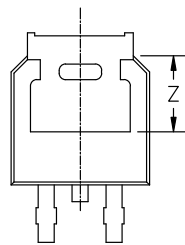
SCALE 1:1



| MILLIMETERS |          |      |       |
|-------------|----------|------|-------|
| DIM         | MIN      | NOM  | MAX   |
| A           | 2.18     | 2.28 | 2.38  |
| A1          | 0.00     | ---  | 0.13  |
| b           | 0.63     | 0.76 | 0.89  |
| b2          | 0.72     | 0.93 | 1.14  |
| b3          | 4.57     | 5.02 | 5.46  |
| c           | 0.46     | 0.54 | 0.61  |
| c2          | 0.46     | 0.54 | 0.61  |
| D           | 5.97     | 6.10 | 6.22  |
| E           | 6.35     | 6.54 | 6.73  |
| e           | 2.29 BSC |      |       |
| H           | 9.40     | 9.91 | 10.41 |
| L           | 1.40     | 1.59 | 1.78  |
| L1          | 2.90 REF |      |       |
| L2          | 0.51 BSC |      |       |
| L3          | 0.89     | ---  | 1.27  |
| L4          | ---      | ---  | 1.01  |
| Z           | 3.93     | ---  | ---   |



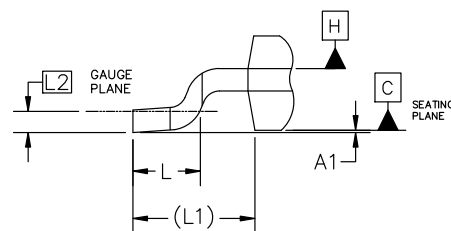
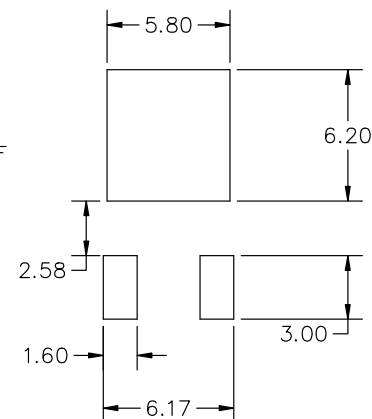
BOTTOM VIEW



ALTERNATE CONSTRUCTIONS

## NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.


DETAIL A  
ROTATED 90° CW


RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

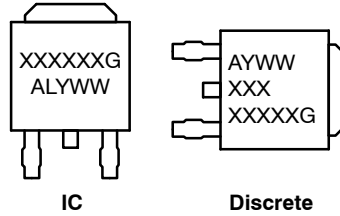
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| <b>DESCRIPTION:</b>     | <b>DPAK-3 6.10x6.54x2.28, 2.29P</b> | <b>PAGE 1 OF 2</b>                                                                                                                                                               |

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**DDAK-3 6.10x6.54x2.28, 2.29P**  
CASE 369C  
ISSUE K

DATE 13 MAY 2026

**GENERIC  
MARKING DIAGRAM\***



XXXXXX = Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

|                                                                       |                                                                       |                                                                  |                                                                            |                                                                   |
|-----------------------------------------------------------------------|-----------------------------------------------------------------------|------------------------------------------------------------------|----------------------------------------------------------------------------|-------------------------------------------------------------------|
| STYLE 1:<br>PIN 1. BASE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | STYLE 2:<br>PIN 1. GATE<br>2. DRAIN<br>3. SOURCE<br>4. DRAIN          | STYLE 3:<br>PIN 1. ANODE<br>2. CATHODE<br>3. ANODE<br>4. CATHODE | STYLE 4:<br>PIN 1. CATHODE<br>2. ANODE<br>3. GATE<br>4. ANODE              | STYLE 5:<br>PIN 1. GATE<br>2. ANODE<br>3. CATHODE<br>4. ANODE     |
| STYLE 6:<br>PIN 1. MT1<br>2. MT2<br>3. GATE<br>4. MT2                 | STYLE 7:<br>PIN 1. GATE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | STYLE 8:<br>PIN 1. N/C<br>2. CATHODE<br>3. ANODE<br>4. CATHODE   | STYLE 9:<br>PIN 1. ANODE<br>2. CATHODE<br>3. RESISTOR ADJUST<br>4. CATHODE | STYLE 10:<br>PIN 1. CATHODE<br>2. ANODE<br>3. CATHODE<br>4. ANODE |

|                  |                              |                                                                                                                                                                                     |
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